

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component comprising: ~~steps of~~
positioning a multi-layered unit formed on a support sheet ~~and including, wherein~~
the multi-layered unit includes a release layer, an electrode layer and a ceramic green sheet, so that a surface of the multi-layered unit is located on a base substrate;
pressing the multi-layered unit toward the base substrate; and
laminating the multi-layered unit on the base substrate, wherein the base substrate has such surface roughness as to include per 0.01 mm² thereof not more than one protrusion that can penetrate the ceramic green sheet of the multi-layered unit laminated on the base substrate to half or more ~~the~~ a thickness of the ceramic green sheet and include per 100 mm² thereof not more than one protrusion that can completely penetrate the ceramic green sheet.

2. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein an agglutinant layer is formed on the base ~~sheet-substrate~~ and the multi-layered unit is positioned on the base substrate so that the surface of the multi-layered unit comes into contact with ~~the~~ a surface of the agglutinant layer and pressed toward the base substrate, thereby laminating the multi-layered unit on the base substrate.

3. (Canceled)

4. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the agglutinant layer is

formed on ~~the~~a surface of the base ~~sheet-substrate~~ in such a manner that ~~the~~a bonding strength between itself and the base substrate is higher than ~~the~~a bonding strength between the support sheet and the release layer and lower than ~~the~~a bonding strength between itself and the ceramic green sheet.

5. (Original) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the agglutinant layer has a thickness of 0.01 μm to 0.3 μm .

6. (Canceled)

7. (Original) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 4, wherein the agglutinant layer has a thickness of 0.01 μm to 0.3 μm .

8. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the agglutinant layer contains a binder belonging to ~~the~~a same binder group as that of a binder contained in the ceramic green sheet ~~belongs to~~.

9. (Canceled)

10. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 4, wherein the agglutinant layer contains a binder belonging to ~~the~~a same binder group as that of a binder contained in the ceramic green sheet ~~belongs to~~.

11. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the agglutinant layer

contains a plasticizing agent belonging to the same binder group as that of a plasticizing agent contained in the ceramic green sheet ~~belongs to~~.

12. (Canceled)

13. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 4, wherein the agglutinant layer contains a plasticizing agent belonging to ~~the~~ a same binder group as that of a plasticizing agent contained in the ceramic green sheet ~~belongs to~~.

14. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the agglutinant layer contains dielectric particles having ~~the~~ a same composition as that of dielectric particles contained in the ceramic green sheet.

15. (Canceled)

16. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 4, wherein the agglutinant layer contains dielectric particles having ~~the~~ a same composition as that of dielectric particles contained in the ceramic green sheet.

17. (Original) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the base substrate is formed of a plastic material selected from a group consisting of polyethylene, polypropylene, polycarbonate, polyphenylene ether and polyethylene terephthalate.

18. (Original) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the base substrate is formed of a plastic material

selected from a group consisting of polyethylene, polypropylene, polycarbonate, polyphenylene ether and polyethylene terephthalate.

19. (Canceled)

20. (Original) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 4, wherein the base substrate is formed of a plastic material selected from a group consisting of polyethylene, polypropylene, polycarbonate, polyphenylene ether and polyethylene terephthalate.

21. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the ceramic green sheet has a said thickness equal to or thinner than 3 μm .

22. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the ceramic green sheet has a said thickness equal to or thinner than 3 μm .

23. (Canceled)

24. (Currently Amended) A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 4, wherein the ceramic green sheet has a said thickness equal to or thinner than 3 μm .